1 Characteristics

Table 1. Absolute ratings (limiting values, at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage		T_j = -40 °C to +175 °C	600	V
$I_{F(RMS)}$	Forward rms current			50	A
$I_{F(AV)}$	Average forward current δ = 0.5, square wave	T_C = 125 °C		30	A
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms sinusoidal	D²PAK, D²PAK HV	180	A
			TO-220AC, DO-247	200	
T_{stg}	Storage temperature range			-65 to +175	°C
T_j	Operating junction temperature range			-40 to +175	°C

Table 2. Thermal parameters

Symbol	Parameter	Max. value	Unit
$R_{th(j-c)}$	Junction to case	0.7	°C/W

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R (1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$	-		40	µA
		T_j = 150 °C		-	80	800	
V_F (2)	Forward voltage drop	T_j = 25 °C	I_F = 15 A	-		2.45	V
		T_j = 150 °C		-	1.15	1.45	
		T_j = 25 °C	I_F = 30 A	-		2.95	
		T_j = 150 °C		-	1.45	1.85	

1. *Pulse test: t_p = 5 ms, δ < 2%*
2. *Pulse test: t_p = 380 µs, δ < 2%*

To evaluate the conduction losses, use the following equation:

$P = 1.05 \times I_{F(AV)} + 0.026 \times I_F{}^2{}_{(RMS)}$

Table 4. Dynamic electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	T_j = 25 °C	I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A	-		30	ns
			I_F = 1 A, V_R = 30 V, dI_F/dt = -50 A/µs	-	40	55	
I_{RM}	Reverse recovery current	T_j = 125 °C	I_F = 30 A, V_R = 400 V, dI_F/dt = -200 A/µs	-	8	11	A
Q_{RR}	Reverse recovery charge			-	485		nC
t_{rr}	Reverse recovery time			-	95		ns

For more information, please refer to the following application notes related to the power losses:

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses in a power diode

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (square waveform)

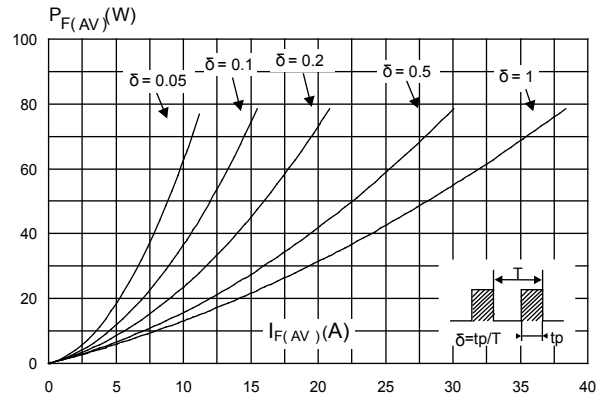


Figure 2. Average forward power dissipation versus average forward current (sinusoidal waveform)

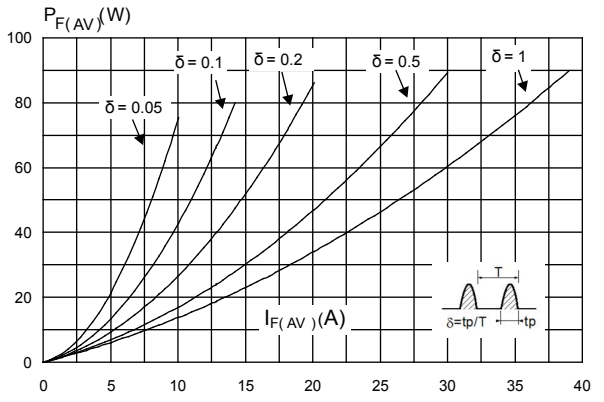


Figure 3. Forward voltage drop versus forward current (typical values)

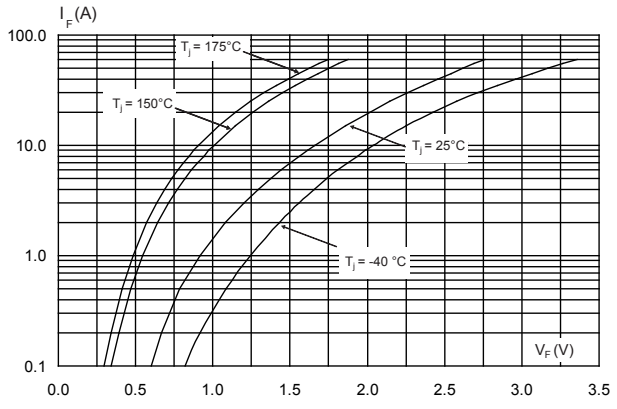


Figure 4. Forward voltage drop versus forward current (maximum values)

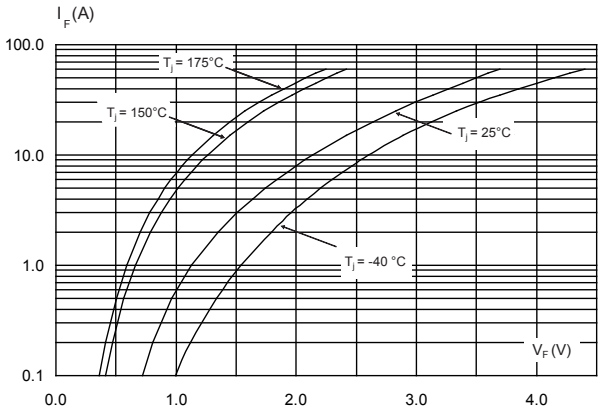


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

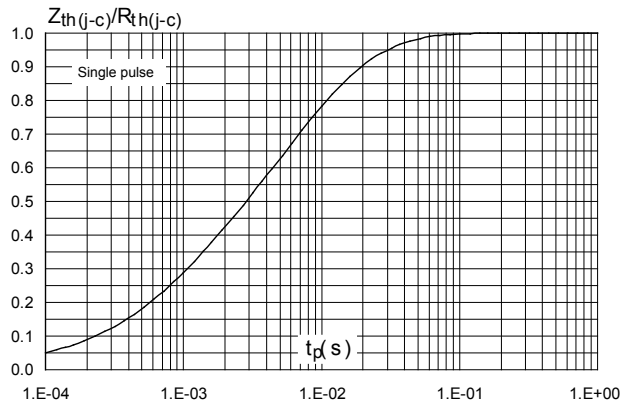


Figure 6. Peak reverse recovery current versus dI_F/dt (typical values)

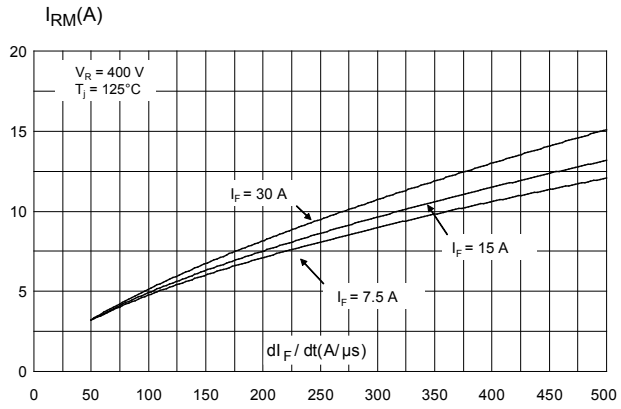


Figure 7. Reverse recovery time versus dI_F/dt (typical values)

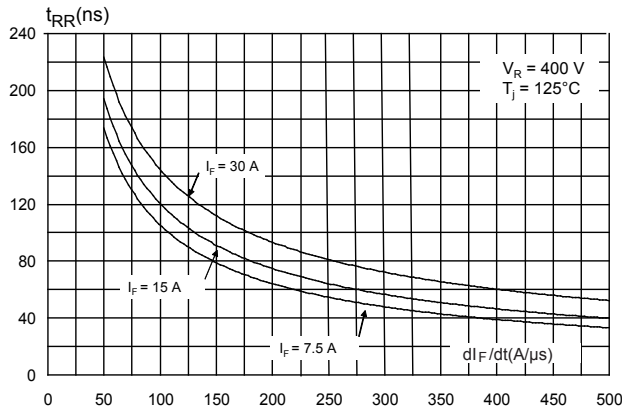


Figure 8. Reverse recovery charges versus dI_F/dt (typical values)

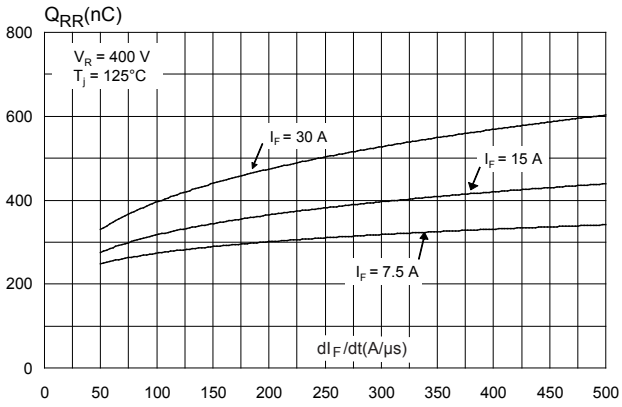


Figure 9. Reverse recovery softness factor versus dI_F/dt (typical values)

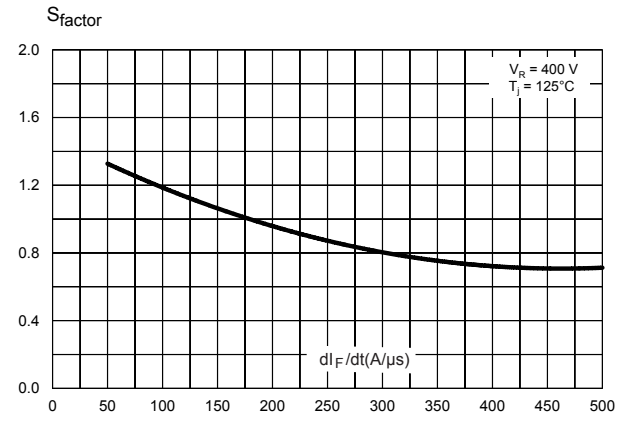


Figure 10. Relative variations of dynamic parameters versus junction temperature

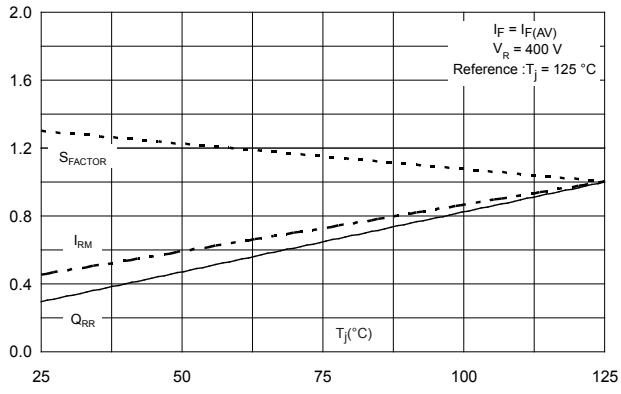


Figure 11. Junction capacitance versus reverse voltage applied (typical values)

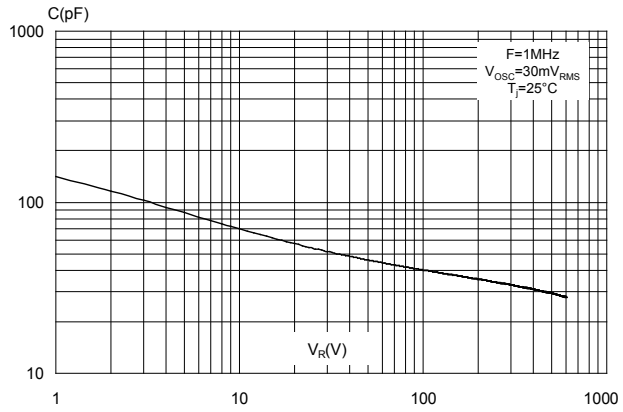


Figure 12. Thermal resistance junction to ambient versus copper surface under tab (typical values, epoxy printed board FR4, e_{Cu} = 35 µm)(D²PAK and D²PAK HV)

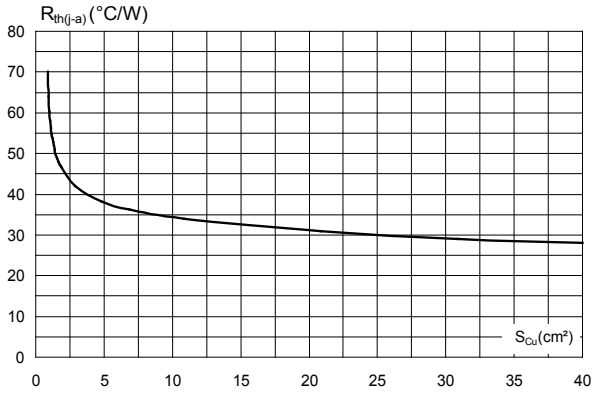


Figure 13. Relative variation of non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

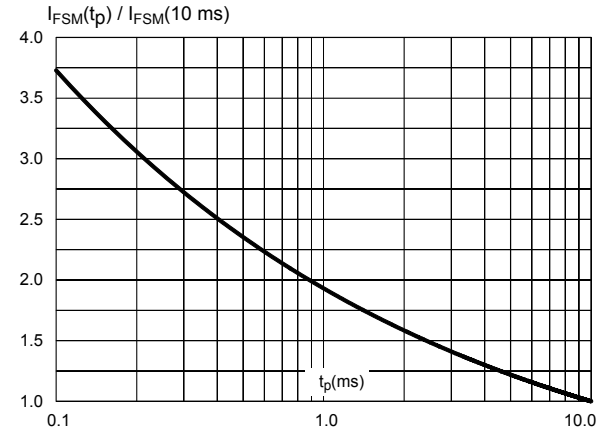
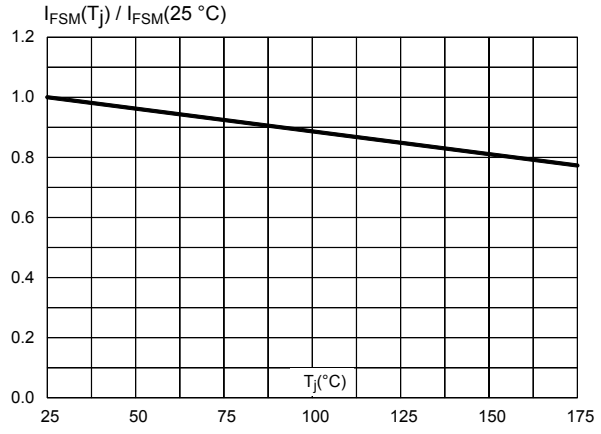


Figure 14. Relative variation of non-repetitive peak surge forward current versus initial junction temperature (sinusoidal waveform)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 DO-247 package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 N·m (DO-247)
- Maximum torque value: 1.0 N·m (DO-247)

Figure 15. DO-247 package outline

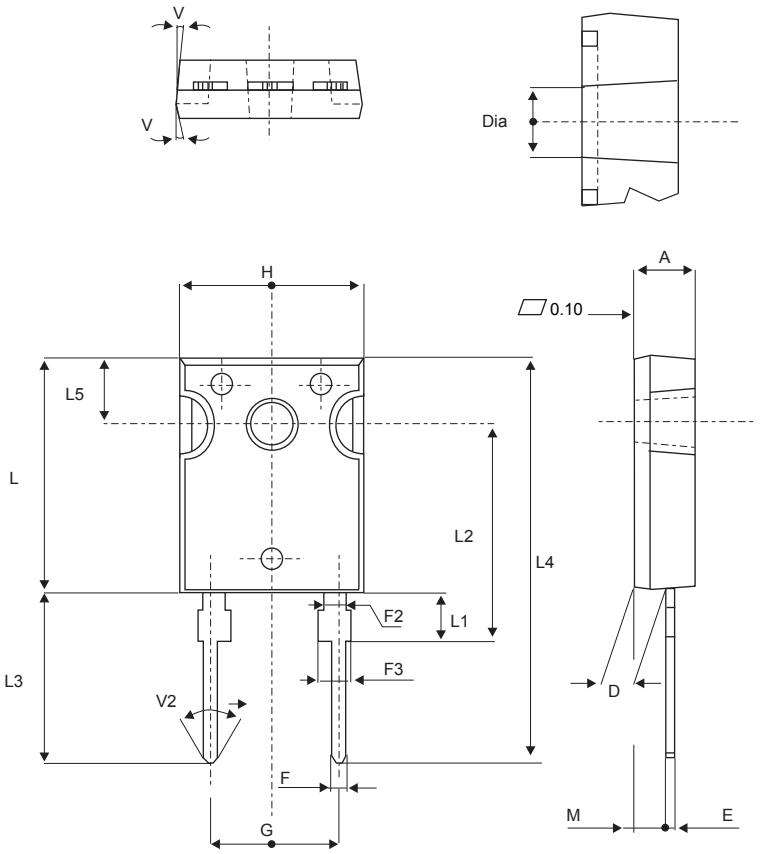


Table 5. **DO-247 package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.85	5.15	0.191	0.203
D	2.20	2.60	0.086	0.102
E	0.40	0.80	0.015	0.031
F	1.00	1.40	0.039	0.055
F2	2.00 typ.		0.078 typ.	
F3	2.00	2.40	0.078	0.094
G	10.90 typ.		0.429 typ.	
H	15.45	15.75	0.608	0.620
L	19.85	20.15	0.781	0.793
L1	3.70	4.30	0.145	0.169
L2	18.50 typ.		0.728 typ.	
L3	14.20	14.80	0.559	0.582
L4	34.60 typ.		1.362 typ.	
L5	5.50 typ.		0.216 typ.	
M	2.00	3.00	0.078	0.118
V	5°		5°	
V2	60°		60°	
Dia.	3.55	3.65	0.139	0.143

2.2 D²PAK package information

- Epoxy meets UL94, V0.
- Cooling method: by conduction (C)

Figure 16. D²PAK package outline

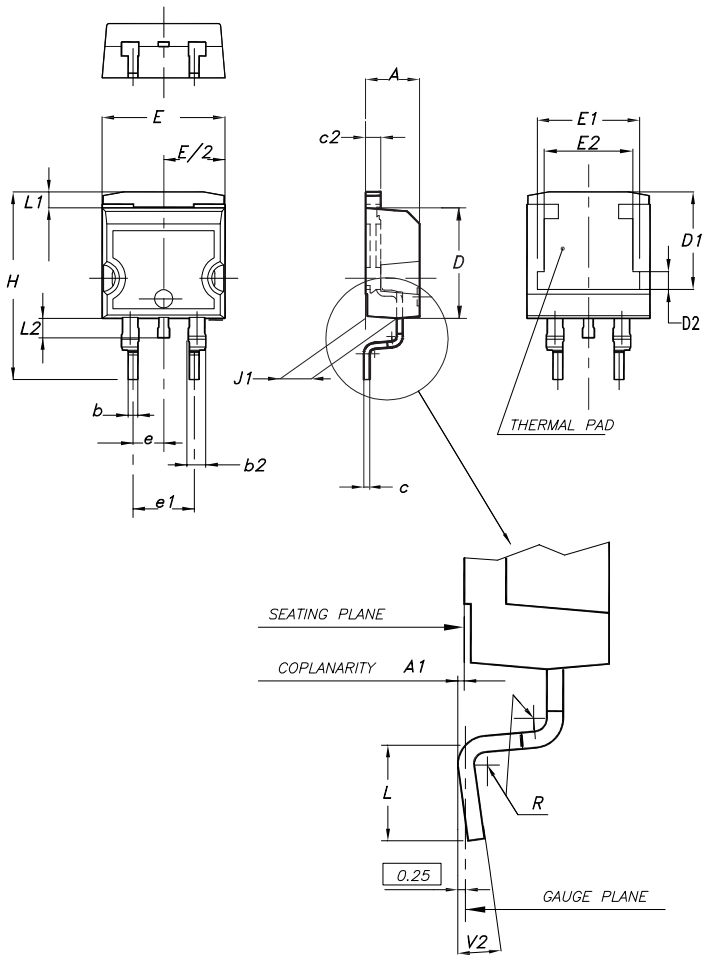
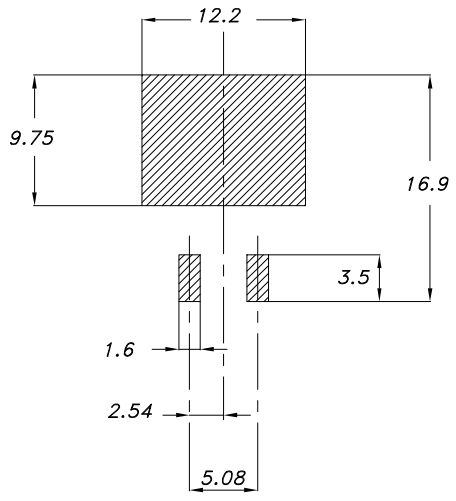


Table 6. **D²PAK package mechanical data**

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.028		0.037
b2	1.14		1.70	0.045		0.067
c	0.45		0.60	0.018		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50	7.75	8.00	0.295	0.305	0.315
D2	1.10	1.30	1.50	0.043	0.051	0.060
E	10.00		10.40	0.394		0.409
E1	8.30	8.50	8.70	0.335	0.343	0.346
E2	6.85	7.05	7.25	0.266	0.278	0.282
e		2.54			0.100	
e1	4.88		5.28	0.190		0.205
H	15.00		15.85	0.591		0.624
J1	2.49		2.69	0.097		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.049		0.055
L2	1.30		1.75	0.050		0.069
R		0.40			0.015	
V2	0°		8°	0°		8°

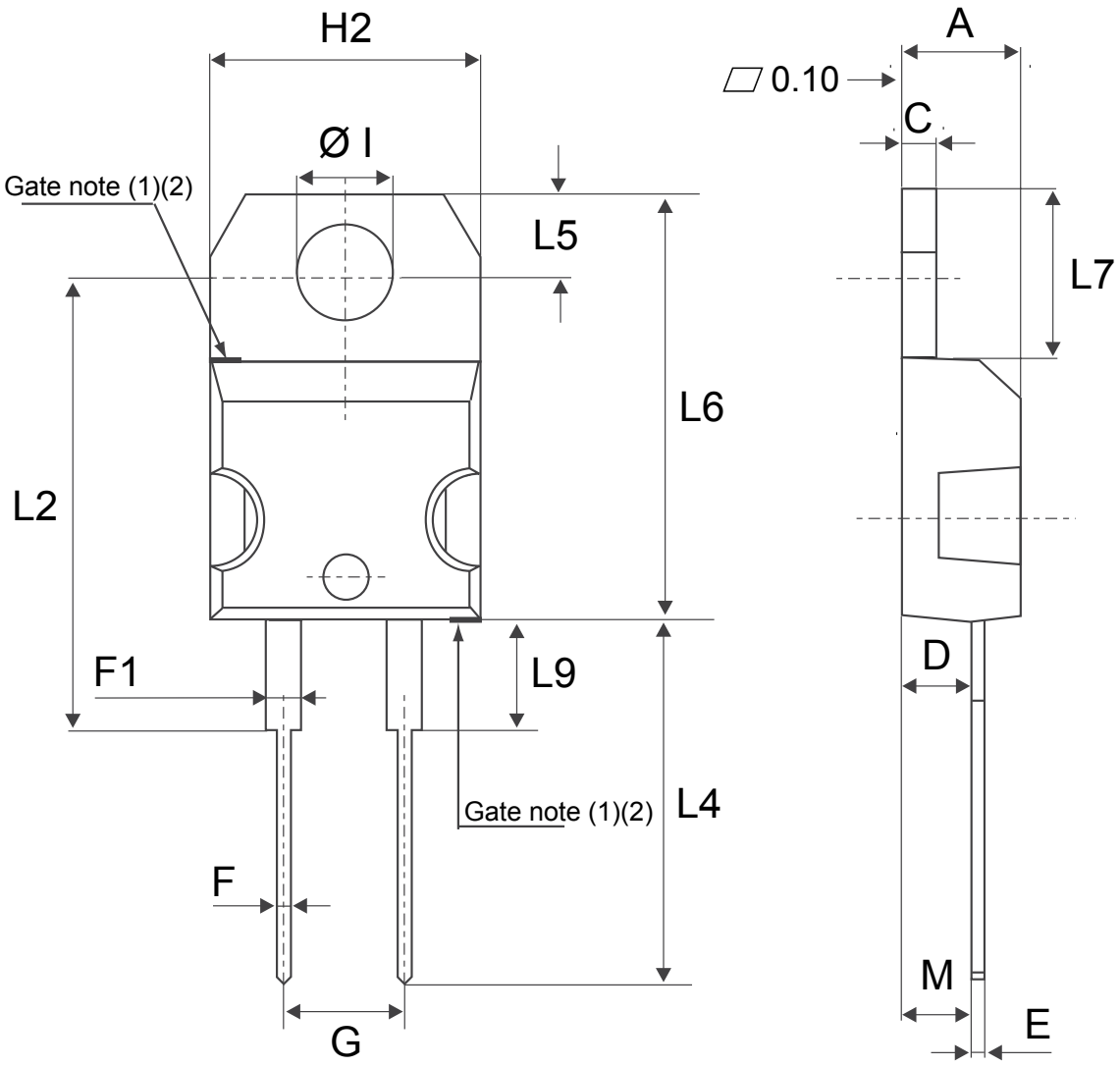
Figure 17. **D²PAK recommended footprint (dimensions are in mm)**



2.3 TO-220AC package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.70 N·m

Figure 18. TO-220AC package outline



(1) :Max resin gate protusion 0.5 mm

(2) :Resin gate position is accepted in each of the two positions shown on the drawings or their symmetrical

Table 7. **TO-220AC package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.60 typ.		0.102 typ.	
Diam	3.75	3.85	0.147	0.151

2.4 D²PAK HV package information

Figure 19. D²PAK high voltage package outline

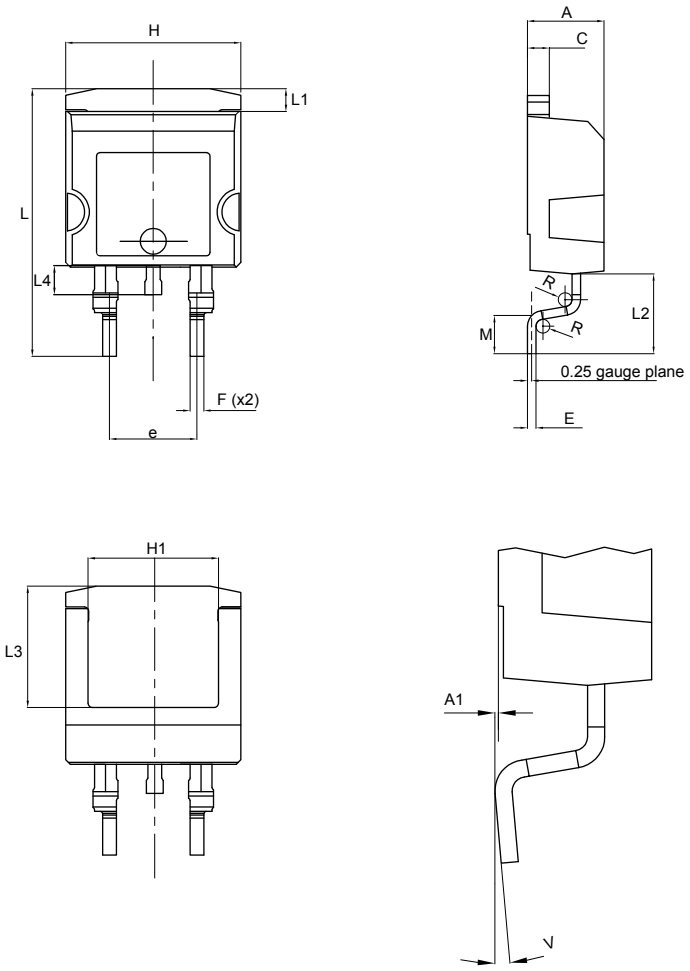
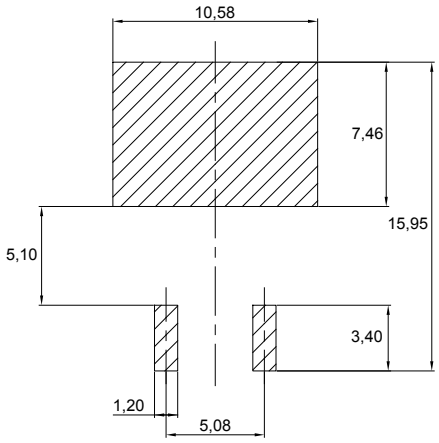


Table 8. D²PAK high voltage package mechanical data

Ref.	Dimensions		
	Min.	Typ.	Max.
A	4.30		4.70
A1	0.03		0.20
C	1.17		1.37
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
H	10.00		10.40
H1	7.40		7.80
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	6.85		7.25
L4	1.5		1.7
M	2.6		2.9
R	0.20		0.60
V	0°		8°

Figure 20. D²PAK High Voltage footprint in mm



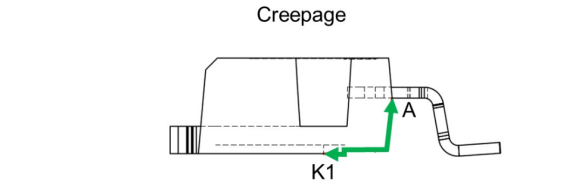
2.4.1 Creepage distance between anode and cathode

Table 9. Creepage distance between anode and cathode

Symbol	Parameter		Value	Unit
Cd_{A-K1}	Minimum creepage distance between A and K1 (with top coating)	D²PAK HV	5.38	mm
Cd_{A-K2}	Minimum creepage distance between A and K2 (without top coating)		3.48	

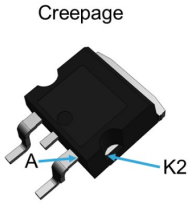
Note: D²PAK HV creepage distance (anode to cathode) = 5.38 mm min. (refer to IEC 60664-1)

Figure 21. Creepage with top coating



Minimum distance between A & K1 = 5.38 mm (with top coating)

Figure 22. Creepage without top coating



Minimum distance between A & K2 = 3.48 mm (without top coating)

3 Ordering information

Table 10. **Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH30RQ06GY-TR	STTH30RQ06GY	D²PAK	1.48 g	1000	Tape and reel
STTH30RQ06DY	STTH30RQ06DY	TO-220AC	1.86 g	50	Tube
STTH30RQ06WY	STTH30RQ06WY	DO-247	4.40 g	30	Tube
STTH30RQ06G2Y-TR	TH30RQ06G2Y	D²PAK HV	1.48 g	1000	Tape and reel

Revision history

Table 11. **Document revision history**

Date	Revision	Changes
12-Jun-2017	1	Initial release.
09-Oct-2018	2	Added D²PAK HV package.
20-Nov-2018	3	Updated Features and Table 9. Creepage distance between anode and cathode. added Figure 22. Creepage without top coating.